



Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment

Marketing Name / Model

[List multiple models if applicable.]

HP F5000-S VPN Firewall Appliance (JG370A)

HP F5000-C VPN Firewall Appliance (JG650A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	3
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw driver	2#
tweezers	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Unscrew the screws on part 1, and then remove part 1.
2. Remove part 2, part 3, part 4.
3. Unscrew the screws on part 2-1, and then remove part 2-1.
4. Unscrew the screws on part 2-2, and then remove part 2-2.
5. Unscrew the screws on pcb 2-3, and then remove pcb 2-3.
6. Unscrew the screws on part 2-4, and then remove part 2-4.
7. Remove part 2-5 and part 2-6.
8. Remove part 4-1.
9. Remove part 5.
10. Remove part 5-1.
11. Unscrew the screws on part 6, and then remove part 6.
12. Unscrew the screws on part 7, and then remove part 7.
13. Remove part 8.
14. Unscrew the screws on pcb 9, part 10, and then remove pcb 9 and part 10 together.
15. Unscrew the screws on pcb 9, and then remove pcb 9 from part 10.
16. Remove part 9-1, part 9-2, part 9-3, part 9-4, part 9-5 from pcb 9.
17. Unscrew the screws on part 9-6, and then remove part 9-6.
18. Unscrew the screws on part 13, and then remove part 13.
19. Unscrew the screws on part 11, and then remove part 11.
20. Remove part 12, part 14, part 15 from part 16.
21. Unscrew the screws on part 11-1 and part 11-3, and then remove part 11-1 and part 11-3.
22. Clear the yellow adhesive, if had, by the tweezers.
23. Pry the button battery up from socket.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations)

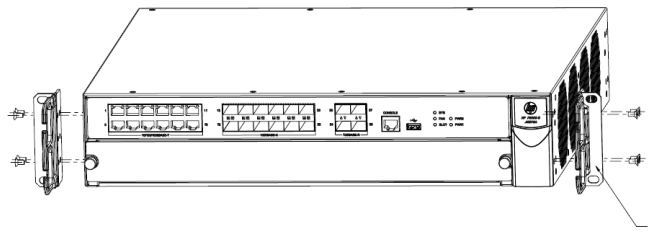


Figure 1 Remove part 1

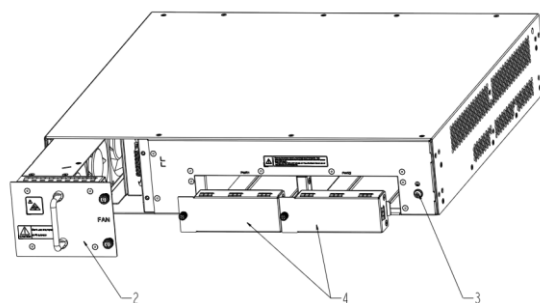


Figure 2 Treatments to the product

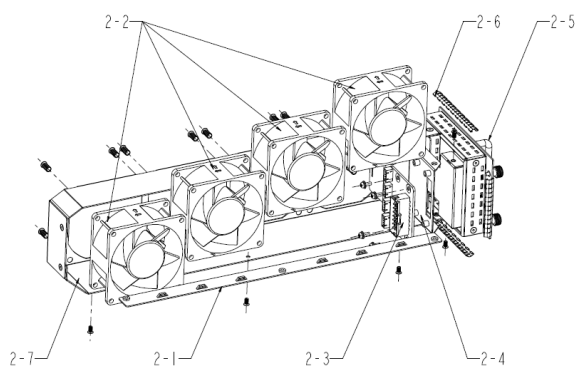


Figure 3 Treatments to the product

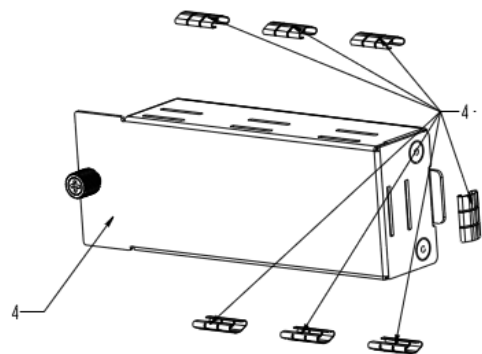


Figure 4 Treatments to the product

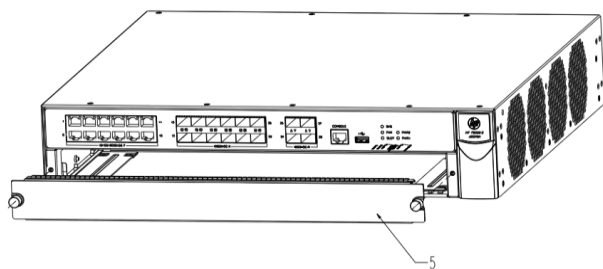


Figure 5 Remove part 5

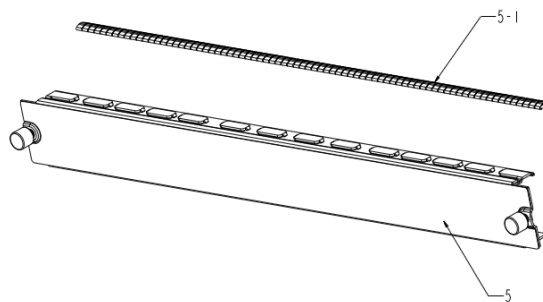


Figure 6 Remove part 5-1

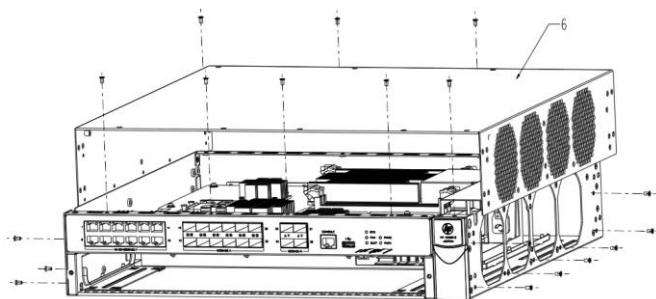


Figure 7 Remove part 6

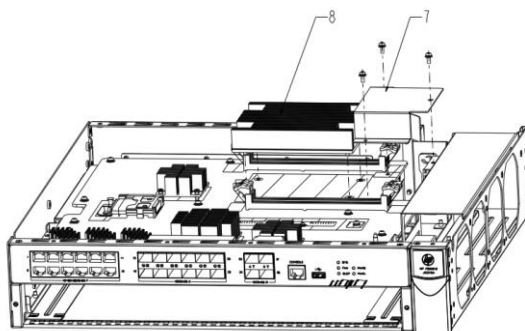


Figure 8 Treatments to the product

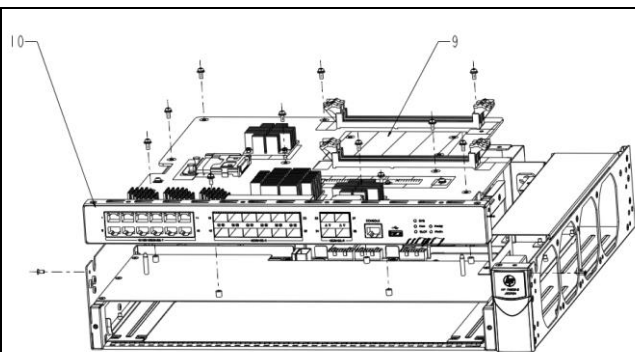


Figure 9 Treatments to the product

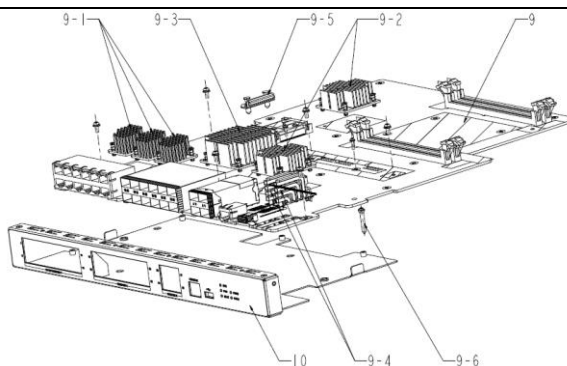


Figure 10 Treatments to the product

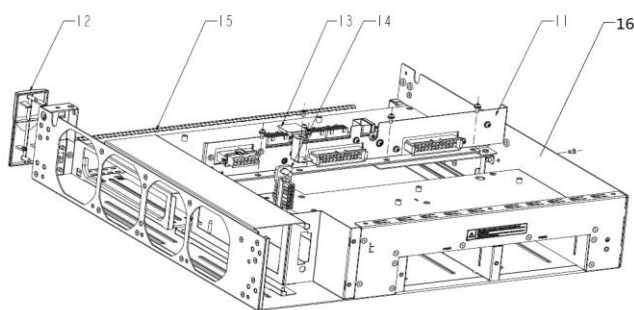


Figure 11 Treatments to the product

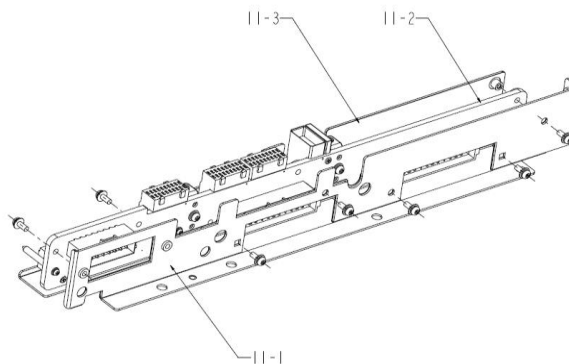


Figure 12 Treatments to the product

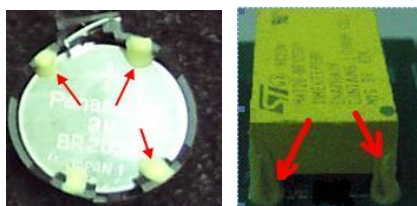


Figure 13 Clear the yellow adhesives by the tweezers

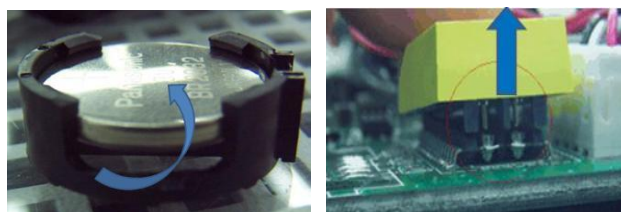


Figure 14 Pry up the button battery

3.3 Material of the facility built

Facility	Components	Material	Weight(g)	Weight percentage	Selective treatment for materials and components	Details
1		Fe,PC+ABS	150	0.01%		Fe recycling
2						
	2-1	Fe	48	0.003%		Fe recycling
	2-2	PBT,Cu	2120	14.5%		Cu recycling
	2-3	Complex PWB	30	0.002%	The surface of PCB is greater than 10 square centimeters;	

	2-4	Fe	62	0.004%		Fe recycling
	2-5	Fe	32	0.002%		Fe recycling
	2-7	Fe	1320	9.05%		Fe recycling
4		Fe	192	1.32%		Fe recycling
5		Fe	290	1.99%		Fe recycling
6		Fe	1940	13.30%		Fe recycling
7		Fe	70	0.004%		Fe recycling
8		Al	190	1.31%		Al recycling
9		Complex PWB	1900	13.03%	The surface of PCB is greater than 10 square centimeters;	
10		Fe	790	5.42%		Fe recycling
11						
	11-1	Fe	130	0.89%		Fe recycling
	11-2	Complex PWB	300	2.06%	The surface of PCB is greater than 10 square centimeters;	
	11-3	Fe	150	1.03%		Fe recycling
12		PC+ABS	10	0.001%		
13		Fe	10	0.001%		Fe recycling
14		PBT,Cu	20	0.002%		Cu recycling
15		Be-Cu	10	0.001%		Cu recycling
16		Fe	4850	33.27%		Fe recycling

4. Revised record

Date	Version	Author	Modify content
2013.06.24	V0	Liu Ziyi	Initial version